ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information			
upplier Inform	ation												
Company name*			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2023-06-12			
Contact Name		Title -	Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewa	rds	Produ	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
uthorized Represen	ntative*	Title -	Title - Representative			Phone - Representative*				Email - Representative*			
Product-Env-Stewa	rds	Produ	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number		Mfr Item Number Mfr Item Name			Effect		Version	N	Manufacturing Site		ight*	UOM	Unit Type
		NCP167BFCT33	30T2G LDO 700 mA, Ul PSRR, Non-Activ	ltra-Low Noise and F ve Discharge	High 20	023-06-12		C	CNG	0.3	13731	mg	Each
Ianufacturing l	Proccess Informatio	n											
Terminal Plating / Grid Array Material		ial Terminal	Ferminal Base Alloy J-STD-020 MSI		ting	Peak Process Body Temperature   Max Time at I		e Max Time at Peak	Temperature	Numbe	er of Reflow Cyc	les	
Matte Tin (Sn) - annealed		CU Allo	CU Alloy 1			260	260 C 30		30	seconds	3		
omments													
vel 1 - maximum ti	ime at peak temperature	during soldering	is 10-30 seconds										
or more informatio	on regarding material cor	nposition please i	refer to page 3										·

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Bump	0.0438	mg	Supplier	Tin (Sn)	7440-31-5		0.0108	mg
			Supplier	Copper (Cu)	7440-50-8		0.033	mg
Die	0.24779	mg	Supplier	Silicon (Si)	7440-21-3		0.2464	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0014	mg
Protection coat	0.00637	mg		Polyimide	proprietary data		0.0064	mg
Under Bump Metal	0.015771	mg	Supplier	Titanium (Ti)	7440-32-6		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.0155	mg